

Listing of the Claims:

The text of all pending claims (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strike through~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

The claims have not been amended. The following list of claims, rather, is presented for the convenience of the reader.

1. (previously presented) A method of forming a via hole by firing a laser beam in a resin layer including an inorganic filler, said method of forming a via hole characterized by including:

a first laser beam firing step of firing onto the resin layer including the inorganic filler a laser beam of a wavelength within the infrared region and not absorbed by the inorganic filler, at a position of said resin layer for forming a via hole so as to expel the resin and said inorganic filler and thereby form a hole in said resin layer; and

a second laser beam firing step of firing a laser beam of a wavelength within the ultraviolet region and capable of cleaving C-C bonds of the resin, focused at a position where said hole is formed to remove a modified layer of the resin remaining at the bottom of said hole and form a via hole with an underlying layer exposed at its bottom.

2. (original) A method of forming a via hole as set forth in claim 1, characterized by: using a CO₂ laser in the first laser beam firing step and using a UV-YAG laser in the second laser beam firing step.

3. (original) A method of forming a via hole as set forth in claim 1, characterized in that said resin layer includes at least one type of inorganic filler among barium titanate, titanium oxide, strontium titanate, and barium-strontium titanate.

4. (original) A method of forming a via hole as set forth in claim 1, characterized in that said resin layer includes an inorganic filler with a dielectric constant of 30 to 15000.

5. (original) A method of forming a via hole as set forth in claim 1, characterized in that said resin layer includes an inorganic filler having a band gap of 3 to 4 eV.

6. (previously presented) A method of forming a via hole by firing a laser beam in a resin layer including an inorganic filler, said method of forming a via hole comprising:

- providing an infrared laser beam not absorbed by the inorganic filler;
- firing the infrared laser beam at a position of said resin layer;
- expelling the resin and the inorganic filler at the position;
- forming a via hole in the resin layer at the position;
- modifying a layer of the resin remaining at the bottom of the via hole;
- providing an ultraviolet laser beam capable of cleaving C-C bonds of the resin;
- firing the ultraviolet laser beam at the position;
- removing the modified layer of the resin remaining at the bottom of the via hole; and
- exposing an underlying layer at the bottom of the via hole by removing the modified layer of the resin.